506224403 08/27/2020

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ULF FILDEBRANDT	12/11/2018
MADHAV BHARGAVA	12/10/2018
SAPREEN AHUJA	12/10/2018
SRIPAD J	12/17/2018

RECEIVING PARTY DATA

Name:	SAP SE	
Street Address:	DIETMAR-HOPP-ALLEE 16	
City:	WALLDORF	
State/Country:	GERMANY	
Postal Code:	69190	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17004597

CORRESPONDENCE DATA

Fax Number: (877)769-7945

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (214) 747-5070 **Email:** APSI@fr.com

Correspondent Name: FISH & RICHARDSON P.C.

Address Line 1: P.O. BOX 1022

Address Line 4: MINNEAPOLIS, MINNESOTA 55440-1022

ATTORNEY DOCKET NUMBER:	22135-1326002	
NAME OF SUBMITTER:	CANDICE R. ROCKETT	
SIGNATURE:	/Candice R. Rockett/	
DATE SIGNED:	08/27/2020	

Total Attachments: 4

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PATENT 506224403 REEL: 053617 FRAME: 0055

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ASSIGNMENT

For valuable consideration, I, Ulf Fildebrandt,

hereby assign to

SAP SE, a corporation of Europe having a place of business at Dietmar-Hopp-Allee 16, 69190 Walldorf, Germany

and its successors, and assigns (collectively, the ASSIGNEE) my entire right, title and interest throughout the world in the inventions and improvements in a patent document entitled:

Load distribution for integration scenarios

which is found in the:

US patent application filed on: 01 October 2018

under Application No. 16/148,008

I authorize and request the attorneys of record or the attorney filing the application to insert into this assignment the filing date and serial number of the application when known. This assignment includes the foregoing patent application or patent, as well as continuations and divisionals of said application, all legal equivalents in any country, and all patents issuing from such legal equivalents; all patents, utility models, and design registrations granted by any jurisdiction for any of said inventions and improvements; and the right to claim priority based on the filing date of the foregoing patent application or patent under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes. I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements. I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with this assignment. I hereby state and agree that no assignment, sale, agreement, or encumbrance has been or will be made or entered into that would conflict with this assignment. I further agree for myself and my heirs, legal representatives, and assigns to provide to the Assignee promptly upon its request and at its expense all pertinent facts and documents relating to any of said inventions and improvements or said patents and legal equivalents as may be known and accessible to me and to testify as to the same in any interference, litigation, or proceeding relating thereto; and I agree promptly to perform such lawful acts and to sign such further applications, assignments, statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Inventor's Signature: Ulf Fildsbrandt 12/11/2018

ASSIGNMENT

For valuable consideration, I, Madhav Bhargava,

hereby assign to

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Inventor's Signature:

Madlian Bhargana

12/10/2018

Madhav Bhargava

ASSIGNMENT

For valuable consideration, I, Sapreen Ahuja,

hereby assign to

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Inventor's Signature:

Sapreur lluya

12/10/2018

Sapreen Ahuja

ASSIGNMENT

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Inventor's Signature: 12/17/2018

Sripad J

Sripad J